UNISONIC TECHNOLOGIES CO., LTD

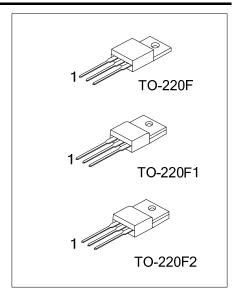
10N50K-MT Power MOSFET

10A, 500V N-CHANNEL POWER MOSFET

■ DESCRIPTION

The UTC 10N50K-MT is an N-channel mode power MOSFET using UTC's advanced technology to provide customers with planar stripe and DMOS technology. This technology allows a minimum on-state resistance and superior switching performance. It also can withstand high energy pulse in the avalanche and commutation mode.

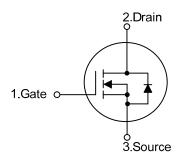
The UTC **10N50K-MT** is generally applied in high efficiency switch mode power supplies, active power factor correction and electronic lamp ballasts based on half bridge topology.



■ FEATURES

- * $R_{DS(ON)} \le 0.68 \Omega$ @ $V_{GS}=10V$, $I_D=5.0A$
- * High Switching Speed
- * 100% Avalanche Tested

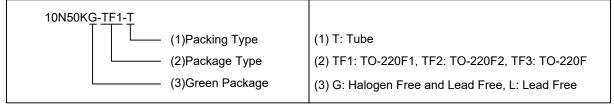
■ SYMBOL



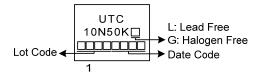
■ ORDERING INFORMATION

Ordering Number		Dookogo	Pin Assignment			Dooking	
Lead Free	Halogen Free	Package	1	2	3	Packing	
10N50KL-TF1-T	10N50KG-TF1-T	TO-220F1	G	D	S	Tube	
10N50KL-TF2-T	10N50KG-TF2-T	TO-220F2	G	D	S	Tube	
10N50KL-TF3-T	10N50KG-TF3-T	TO-220F	G	D	S	Tube	

Note: Pin Assignment: G: Gate D: Drain S: Source



■ MARKING



10N50K-MT Power MOSFET

■ ABSOLUTE MAXIMUM RATINGS (T_C=25°C, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT	
Drain-Source Voltage		V_{DSS}	500	V	
Gate-Source Voltage		V_{GSS}	±30	V	
Drain Current	Continuous (T _C =25°C)	I _D	10 (Note 2)	Α	
	Pulsed (Note 3)	I _{DM}	20 (Note 2)	Α	
Avalanche Current (Note 3)		I _{AR}	10	Α	
Avalanche Energy	nche Energy Single Pulsed (Note 4)		470	mJ	
Peak Diode Recovery dv/dt (Note 5)		dv/dt	3.2	V/ns	
Power Dissipation		Б	48	W	
Derate above 25°C		P_D	0.38	W/°C	
Junction Temperature		TJ	+150	°C	
Storage Temperature		T _{STG}	-55 ~ +150	°C	

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.

- 2. Drain current limited by maximum junction temperature.
- 3. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 4. L = 30mH, I_{AS} = 5.6A, V_{DD} = 50V, R_G = 25 Ω , Starting T_J = 25 $^{\circ}$ C
- 5. $I_{SD} \le 10A$, di/dt $\le 200A/\mu s$, $V_{DD} \le BV_{DSS}$, Starting $T_J = 25^{\circ}C$

■ THERMAL DATA

PARAMETER	SYMBOL	RATINGS	UNIT	
Junction to Ambient	θЈА	62.5	°C/W	
Junction to Case	θјс	2.58	°C/W	

Note: Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

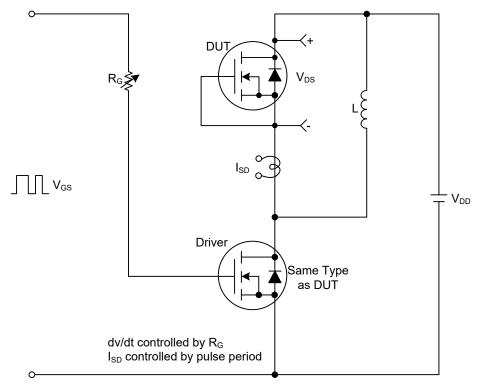
■ **ELECTRICAL CHARACTERISTICS** (TJ=25°C, unless otherwise specified)

PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
OFF CHARACTERISTICS								
Drain-Source Breakdown Voltage		BV _{DSS}	I _D =250μA, V _{GS} =0V	500			V	
Drain-Source Leakage Current		I _{DSS}	V _{DS} =500V, V _{GS} =0V			10	μA	
Gate- Source Leakage Current	Forward		V _{GS} =+30V, V _{DS} =0V			+100	nA	
	Reverse	I _{GSS}	V _{GS} =-30V, V _{DS} =0V			-100	nA	
ON CHARACTERISTICS								
Gate Threshold Voltage		$V_{GS(TH)}$	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	2.0		4.0	V	
Static Drain-Source On-State Resistance		R _{DS(ON)}	V _{GS} =10V, I _D =5.0A			0.68	Ω	
DYNAMIC PARAMETERS								
Input Capacitance		C _{ISS}			1300		pF	
Output Capacitance		Coss	V _{GS} =0V, V _{DS} =25V, f=1.0MHz		140		pF	
Reverse Transfer Capacitance		C_{RSS}			9		pF	
SWITCHING PARAMETERS								
Total Gate Charge		Q_{G}	\\ -400\\ \\ -401\\ -401\\		35		nC	
Gate to Source Charge		Q_GS	V _{DS} =400V, V _{GS} =10V, I _D =10A (Note 1, 2)		11		nC	
Gate to Drain Charge		Q_GD	(Note 1, 2)		10		nC	
Turn-ON Delay Time		$t_{D(ON)}$			22		ns	
Rise Time		t_R	V _{DD} =100V, V _{GS} =10V, I _D =10A,		23		ns	
Turn-OFF Delay Time		t _{D(OFF)}	R _G =25Ω (Note 1, 2)		90		ns	
Fall-Time		t_{F}			30		ns	
SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS								
Maximum Body-Diode Continuous Current		Is				10	Α	
Maximum Body-Diode Pulsed Current		I _{SM}				20	Α	
Drain-Source Diode Forward Voltage		V _{SD}	I _S =10A, V _{GS} =0V			1.4	V	
Body Diode Reverse Recovery Time		t _{rr}	I _S =10A, V _{GS} =0V,		320		nS	
Body Diode Reverse Recovery Charge		Qrr	dl _F /dt=100A/µs		8		μC	

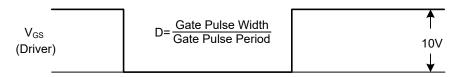
Notes: 1. Pulse Test: Pulse width ≤ 300µs, Duty cycle ≤ 2%.

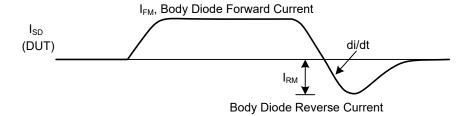
^{2.} Essentially independent of operating temperature.

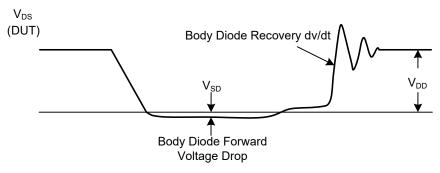
■ TEST CIRCUITS AND WAVEFORMS



Peak Diode Recovery dv/dt Test Circuit & Waveforms

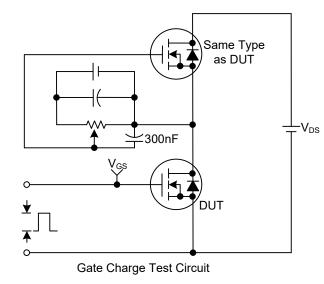


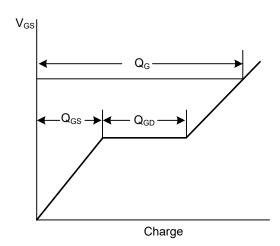




Peak Diode Recovery dv/dt Waveforms

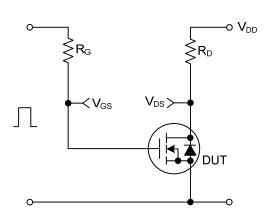
■ TEST CIRCUITS AND WAVEFORMS



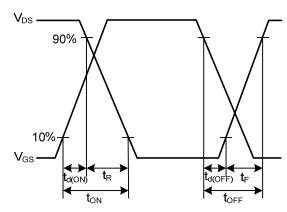


Power MOSFET

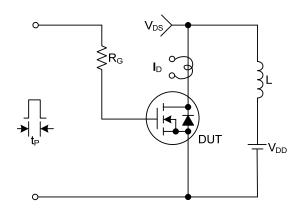
Gate Charge Waveforms



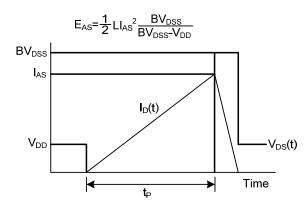
Resistive Switching Test Circuit



Resistive Switching Waveforms

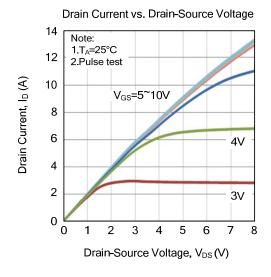


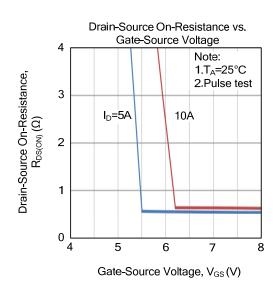
Unclamped Inductive Switching Test Circuit

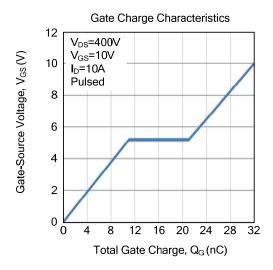


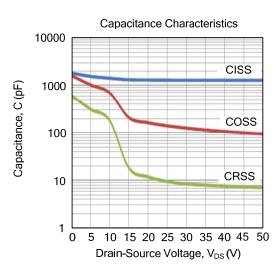
Unclamped Inductive Switching Waveforms

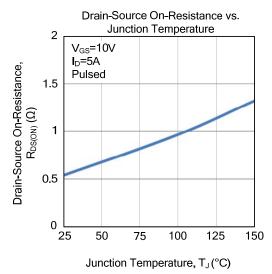
■ TYPICAL CHARACTERISTICS

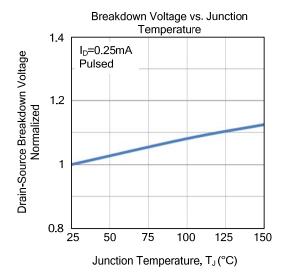




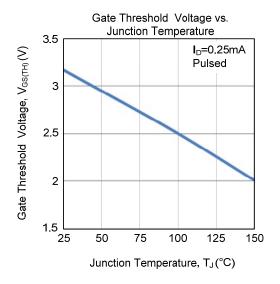


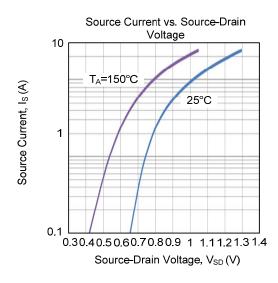


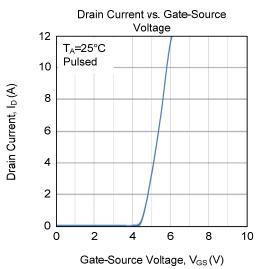


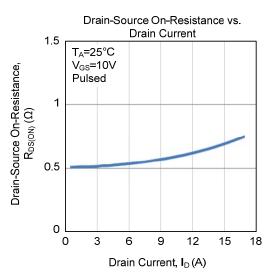


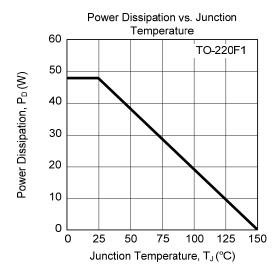
■ TYPICAL CHARACTERISTICS (Cont.)

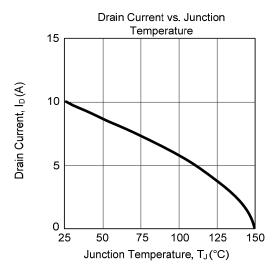




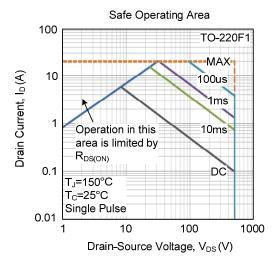








■ TYPICAL CHARACTERISTICS (Cont.)



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